

## in Silicone resin

Solvent based coatings

Evonik Tego formulation No. AC 1000 9 002

Rev. Number: 01.01

10/20

Function	Product	Producer	PBW
Methyl silicone resin	SILIKOPHEN® AC 1000	Evonik	37.00
Solvent	Xylene		18.00
Wetting and dispersing agent	TEGO® Dispers 628	Evonik	2.00
Substrate wetting agent	TEGO® Wet 270	Evonik	0.10
Rheology modifier	BENTONE® SD-1	Elementis	2.00
Muscovite mica	MICA TM	Aspanger	15.00
Anticorrosive pigment	HEUCOPHOS® ZPO	Sudarshan	5.00
Copper chromite black spinel	HEUCODUR® Black 9-100	Sudarshan	8.00
Rheology modifier	AEROSIL® R 972	Evonik	1.60
Grind with a bead mill.			
Solvent	Butyl glycol acetate		2.30
Solvent	Xylene		9.00
Add while stirring.			
			100.00

## Specifications

Vol.-% Anticorrosive pigment reg. pigment/filler	13.5
PVC in %	24.4
Solids in %	70.0

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